

Description

The DMP6180SK3Q-13 uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



TO-252-2L

General Features

V_{DS} =- 60V, I_D =-20A

 $R_{DS(ON)} < 58m\Omega$ @ $V_{GS}=-10V$

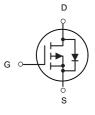
 $R_{DS(ON)}$ < 67m Ω @ V_{GS} =-4.5V

Application

PWM applications

Load switch

Power management



P-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
DMP6180SK3Q-13	TO-252-2L	HXY MOSFET	2500

Absolute Maximum Ratings (TA=25℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
VDS	Drain-Source Voltage	-60	V
VGS	Gate-Source Voltage	±20	V
I _D (25°C)		-20	Α
I _D (70°C)	Drain Current-Continuous@ Current-Pulsed (Note 1)	-12	Α
IDM		-30	Α
PD	Maximum Power Dissipation	25	W
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 175	°C
Reja	Thermal Resistance,Junction-to-Ambient (Note 2)	65	°C/W

P-Channel Enhancement Mode MOSFET

Electrical Characteristics (TA=25 °C unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV_{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-60			V	
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25°C, I _D =-1mA		-0.023		V/°C	
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-10A	=-10V , I _D =-10A 4		58	mO	
	Static Drain-Source On-Resistance	V _{GS} =-4.5V , I _D =-6A		56	67	mΩ	
$V_{GS(th)}$	Gate Threshold Voltage	V -V I - 2500A	-1.2		-2.5	V	
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=-250uA$		4		mV/°C	
	Drain-Source Leakage Current	V _{DS} =-24V , V _{GS} =0V , T _J =25°C			-1	uA	
I_{DSS}		V _{DS} =-24V , V _{GS} =0V , T _J =55°C			-5		
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-15A		12		S	
Qg	Total Gate Charge (-4.5V)			6.1		nC	
Q _{gs}	Gate-Source Charge	V _{DS} =-15V , V _{GS} =-4.5V , I _D =-15A		3.1			
Q _{gd}	Gate-Drain Charge			1.8			
$T_{d(on)}$	Turn-On Delay Time			2.6			
Tr	Rise Time	V_{DD} =-15V , V_{GS} =-10V , R_{G} =3.3 Ω ,		8.6		ns	
$T_{d(off)}$	Turn-Off Delay Time	I _D =-15A		33.6			
T _f	Fall Time			6			
C _{iss}	Input Capacitance			585			
C _{oss}	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		100		pF	
C _{rss}	Reverse Transfer Capacitance			85			
Is	Continuous Source Current ^{1,5}	V -V -0V Faras Ourset			-20	Α	
I _{SM}	Pulsed Source Current ^{2,5}	V _G =V _D =0V , Force Current			-30	Α	
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C			-1.2	V	
t _{rr}	Reverse Recovery Time	IF=-15A , dI/dt=100A/μs ,		6.1		nS	
Q _{rr}	Reverse Recovery Charge	T _J =25°C		1.4		nC	

Note:

^{1.} The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

^{2.}The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

^{3.} The EAS data shows Max. rating . The test condition is V_{DD} =-25V, V_{GS} =-10V, L=0.1mH, I_{AS}=-19A

^{4.} The power dissipation is limited by 150°C junction temperature

^{5.} The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Electrical And Thermal Characteristics

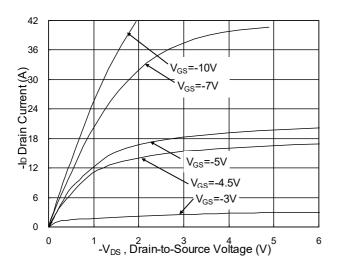


Fig.1 Typical Output Characteristics

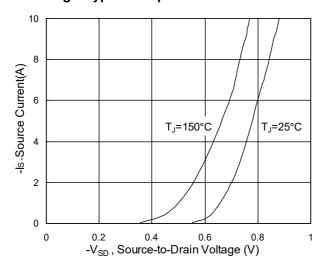


Fig.3 Forward Characteristics Of Reverse

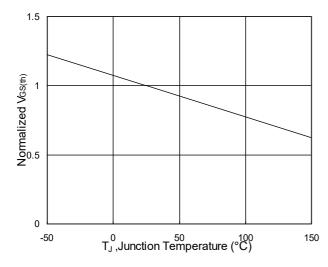


Fig.5 Normalized V_{GS(th)} vs. T_J

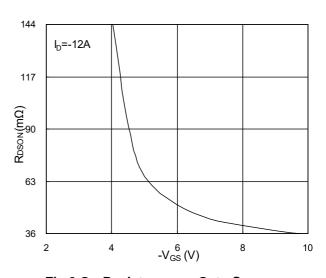


Fig.2 On-Resistance v.s Gate-Source

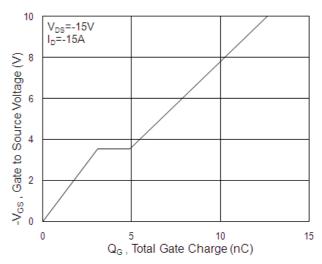


Fig.4 Gate Charge Characteristics

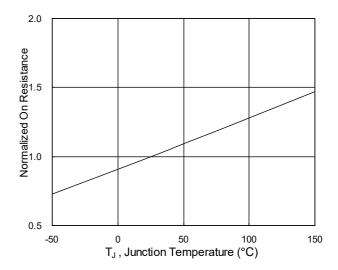
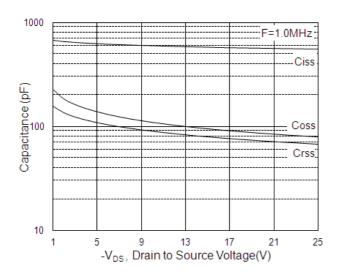


Fig.6 Normalized R_{DSON} vs. T_J





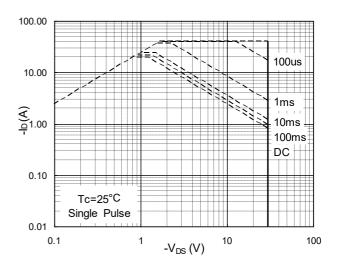


Fig.7 Capacitance

Fig.8 Safe Operating Area

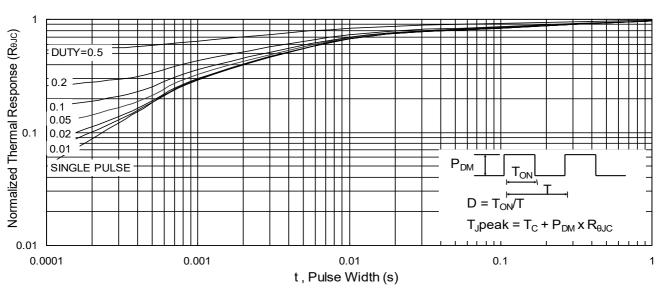


Fig.9 Normalized Maximum Transient Thermal Impedance

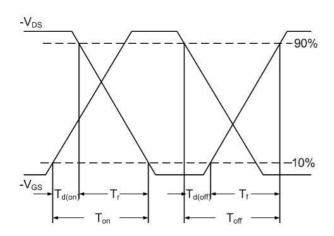


Fig.10 Switching Time Waveform

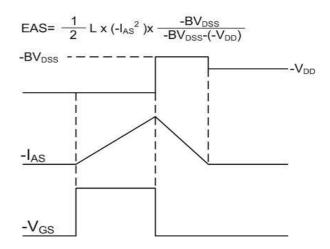
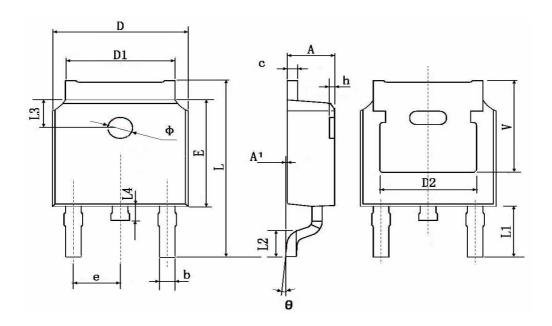


Fig.11 Unclamped Inductive Switching Waveform



TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3		1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	TYP.	0.211 TYP.		

P-Channel Enhancement Mode MOSFET

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